Reg. No. :	
Name :	
VII Semester B.Tech. Degree (Reg./Supple./Improv. – Examination, November 2012 (2007 Admn. Onwards) PT2K6/2K6 EC 701 : MICROELECTRONICS 1	-
Time: 3 Hours	Max.Marks: 100
PART – A	
I. a) Explain dry etching. Give one example.	5
b) Briefly explain about Schottky contacts.	5
c) What is MTF? What is its importance?	5
d) What is sub threshold conduction and DIBL effect?	5
e) Draw the VTC of Bi CMOS inverter and explain.	5
f) Briefly describe $\boldsymbol{\lambda}$ base design rules for metals and pad	s. 5
g) Discuss the isolation process for bipolar IC process.	5
h) Briefly describe scattering in nano transistors.	5
PART-B	
II. a) Derive the analytical model for oxidation. OR	15
b) With a neat diagram, explain CVD process for Si.	15
III. a) Compare early bipolar and advanced bipolar process w	ith suitable diagráms. 15
OR	•
b) i) What are hot carrier?	5
ii) How hot carries affect the performance of BJT and MG	OS? 10

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V. a) i) Realize the logic function $Y = A \oplus B$ using CMOS logic family and draw its	
stick diagram.	10
ii) Draw the stick diagram of CMOS inverter.	5
OR	
b) Realize a 4 bit full added using CMOS. Draw its stick diagram.	15
V. a) Write short notes on.	
i) LOCOS	7
ii) SWAMI	8
OR	
b) Write short notes on	
i) Junction Isolation and Trench Isolation.	10
ii) Ballistic nano transistors.	5